

5 introducing a second agent comprising hydrogen peroxide [onto the] to a  
6 metal [layer] plug.

9 (Amended) A method of removing at least one particle from a portion of a  
metal layer on a substrate comprising:  
depositing a slurry onto the substrate;  
polishing the metal layer and the substrate; and  
rinsing [the substrate] a metal plug with a solution comprising hydrogen  
peroxide.

12. (Amended) The method of claim 9, wherein rinsing the [substrate] metal  
plug occurs after polishing the metal layer and substrate.

13. (Amended) The method of claim 9, wherein rinsing the [substrate] metal  
plug comprises rinsing with the solution which comprises approximately 4% by  
volume or less of hydrogen peroxide.

14. The method of claim 9, wherein polishing the metal layer includes removing  
the metal

18. (Amended) A method of polishing a metal layer on a substrate comprising:  
polishing the metal layer and introducing a rinsing solution onto [the] a  
metal [layer] plug, the rinsing solution comprising hydrogen peroxide.

19. (Amended) The method of claim 18, further including polishing the  
[substrate] metal layer with an abrasive material, wherein the rinsing solution is  
introduced after a polishing of the substrate.